



BGA/CSP DEVELOPMENT UPDATE SERVICE

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The second quarterly BGA/CSP update for 2002 features trends in packaging for mobile phones. Included are mobile phone trends in Japan and a special section on mobile phone packaging developments by domestic Chinese manufacturers. A special section is devoted to IC package assembly price trends, including PQFPs and PBGAs with both wire bonding and flip chip interconnect. Several flip chip and high performance substrate suppliers are profiled, with an emphasis on substrate for flip chip interconnect and substrate price trends. Wafer level packages in production from Micron Technology and Littelfuse are presented and wafer level burn-in test and fabrication from ACE is discussed. New package developments include flip chip on lead frames from AIT, Carsem, and Toshiba, Fairchild's optocoupler BGA, and Mitsubishi's high pin count package using flip chip interconnect. Tessera's new stacked package and a new interposer from Sweden-based Strand Interconnect are also described.

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